

# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide ultra-low Rds(ON) and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

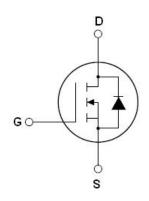
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- New technology for high voltage device
- ●Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ■ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger(OBC)

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub>	85	mΩ
ID	36	Α
Qg	55	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

#### **Package Marking And Ordering Information**

Device	Device Package	Marking	
NCE65NF099D	TO-263	NCE65NF099D	



TO-263

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Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vgs=0V)	VDS	650	V
Gate-Source Voltage (V <sub>DS</sub> =0V) AC (f>1 Hz)	V <sub>G</sub> S	±30	V
Gate-Source Voltage (V <sub>DS</sub> =0V) DC	V <sub>G</sub> S	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	36	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	25.2	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	108	Α
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	346	W
Derate above 25°C		2.30	w/°C
Single pulse avalanche energy (Note 2)	Eas	324	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AS</sub>	9	Α
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	E <sub>AR</sub>	3.9	mJ



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Parameter	Symbol	Value	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55+175	°C

<sup>\*</sup> limited by maximum junction temperature

**Table 2. Thermal Characteristic** 

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.43	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			400	μΑ
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =500uA	3	4	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =18A		85	99	mΩ
Dynamic Characteristics						
Input Capacitance	Clss	.,		2800	3200	pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		96		pF
Reverse Transfer Capacitance	Crss	F=1.0MHz		6		pF
Total Gate Charge	Qg			55	60	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =18A,		16.5		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		25.5		nC
Gate plateau voltage	Vgp			7.3		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1.5		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			15		nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =18A,		14		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=1.7\Omega, V_{GS}=10V$		72		nS
Turn-Off Fall Time	t <sub>f</sub>			14		nS
Source- Drain Diode Characteristics			•	•		
Source-drain current(Body Diode)	I <sub>SD</sub>	Tc=25°C			36	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>				108	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =36A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =18A,di/dt=100A/μs		160		nS
Reverse Recovery Charge	Qrr			0.96		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			12		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> Tj=25 °C,VDD=50V,VG=10V, R\_G=25 $\Omega$ 



#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

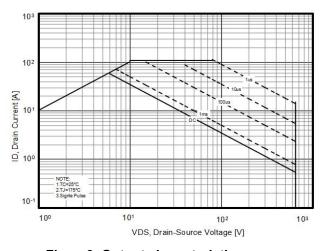


Figure 3. Output characteristics

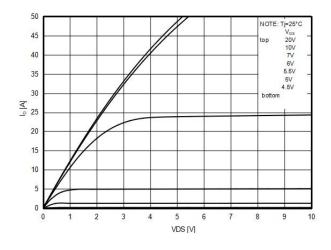


Figure 5. Static drain-source on resistance

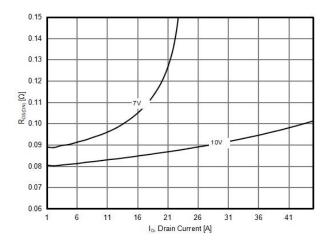


Figure 2. Capacitance

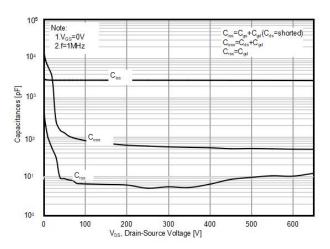


Figure 4. Source-Drain Diode Forward Voltage

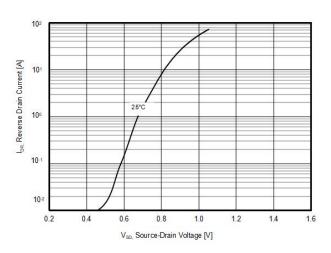
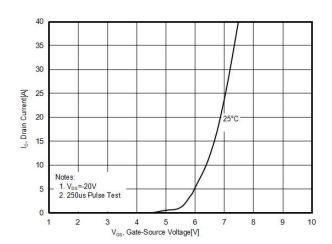


Figure 6. Transfer characteristics



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Figure 7. R<sub>DS(ON)</sub> vs Junction Temperature

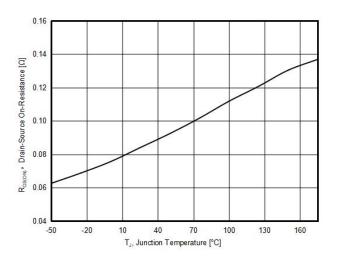


Figure 8. BV<sub>DSS</sub> vs Junction Temperature

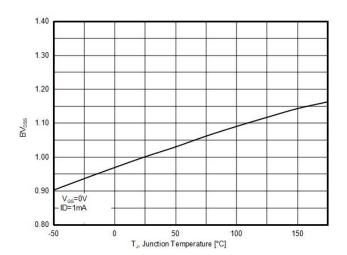


Figure 9. Gate charge waveforms

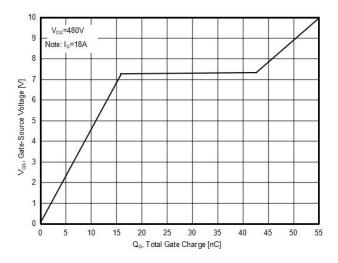
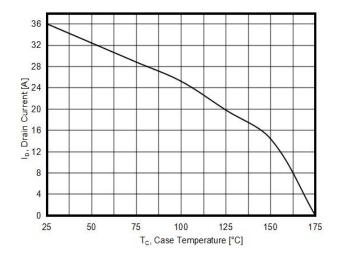


Figure 10. Maximum I<sub>D</sub> vs Junction Temperature

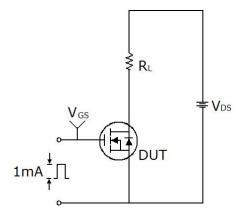


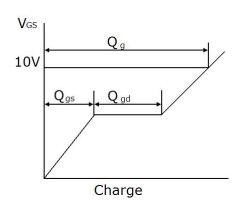
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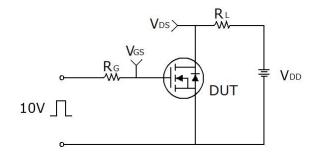
## **Test circuit**

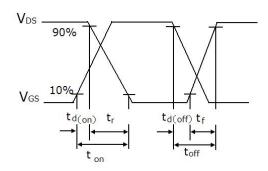
#### 1) Gate charge test circuit & Waveform



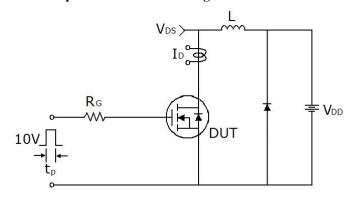


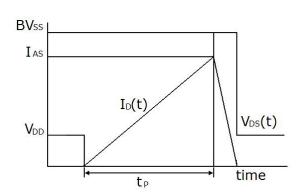
#### 2) Switch Time Test Circuit:





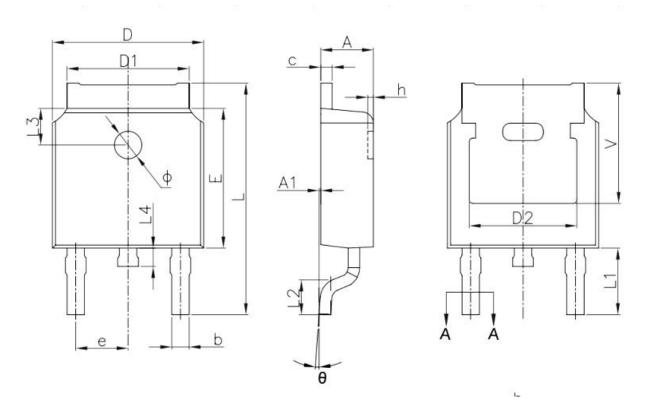
### 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-263** (E) Package Information



Symbol	Dimensions In Millimeters		Dimensions	In Inches
	Min.	Max.	Min.	Max.
A	4.20	4.60	0.165	0.181
A1	-	0.25	-	0.010
A2	2.20	2.60	0.087	0.102
b	0.70	0.90	0.028	0.035
b2	1.17	1.37	0.046	0.054
С	0.40	0.60	0.016	0.024
c1	1.15	1.40	0.045	0.055
D	9.10	9.30	0.358	0.366
D1	7.63	8.23	0.300	0.324
Е	10.05	10.45	0.396	0.411
E1	8.35	8.95	0.329	0.352
е	2.54	2.54 BSC		BSC
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.36REF		0.053REF	
L2	1.3i	1.3REF		REF
L3	0.25REF 0.009REF		REF	



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